



## Material declaration form

General Information			
IPC	1752	Version	2
Form type*	Distribute		
Sectionals*	Material information	Subsectionals*	A-D
	Manufacturing information		

Supplier Information			
Company name*	STMicroelectronics	Response Date*	2025-02-26
Contact name*	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact phone*	Refer to Supplier Comment section	Contact email*	Refer to Supplier Comment section
Authorized representative*	MDG CHAMPION	Representative title	MDGMaterial Declaration champion
Representative phone*	Refer to Supplier Comment section	Representative email*	Refer to Supplier Comment section
Supplier comment	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty statement**

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**Legal statement**

Supplier acceptance*	true	Legal declaration*	Standard
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Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.



Product				
Mfr item number	Mfr item name	Version	Manufacturing site	date
STM32H562ZIT6	251A*484XXXX	A	9991	2025-02-26
	Amount	Unit of measure	Unit type	ST ECOPACK grade
	1286	mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL rating	Classification temperature	Number of reflow cycles		
3	260	3		
Bulk solder termination	Terminal plating	Terminal base alloy	Comment	
Not Applicable	Tin (Sn), matte, annealed	Copper Alloy	0	
Package designator	Package size	Number of instances	Shape	
QFP	20x20	144	Gull wing	
Comment	Package : 1A LQFP 144 20X20X1.4 2 0099183			

QueryList : RoHS Directive 2011/65/EU - 8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015		Response
1 - Product(s) meets EU RoHS requirement without any exemptions		true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)		false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)		false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions		false
Exemption Id.	Description	
,		

QueryList : REACH-21st January 2025				Response
QUERY				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
,	#N/A			



Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	251A*484XXX		1286.4870		6000000.0	1000000.0				
Homogeneous material	Material group	Mass	Unit of measure	Level	Substance category	Substance	CAS	Exempt	Mass	Unit of measure	Concentration in homogeneous material (ppm)	Concentration in product (ppm)				
Die or dies	M-011 Other inorganic materials	11.526	mg	supplier	die	Silicon (Si)	7440-21-3		11.006	mg	954831.4458	8554.87				
				supplier	metallization	Aluminium (Al)	7429-90-5		0.037	mg	3179.018478	28.48				
				supplier	metallization	Copper (Cu)	7440-50-8		0.237	mg	20531.161	183.95				
				supplier	metallization	Cobalt (Co)	7440-48-4		0.001	mg	66.22955163	0.59				
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.033	mg	2847.87072	25.52				
				supplier	metallization	Tungsten (W)	7440-33-7		0.106	mg	9205.907676	82.48				
				supplier	Passivation	Silicon Nitride	12033-89-5		0.027	mg	2384.263859	21.36				
				supplier	Passivation	Silicon Oxide	7631-86-9		0.080	mg	6954.102921	62.31				
				Leadframe (C7025 + Ag)	Copper & its alloys	330.000	mg	supplier	Leadframe	Copper ( Cu )	7440-50-8		315.975	mg	957500	245610.71
								supplier	Leadframe	Nickel ( Ni )	7440-02-0		9.834	mg	29800	7644.07
supplier	Leadframe	Silicon ( Si )	7440-21-3						2.145	mg	6500	1667.33				
supplier	Leadframe	Magnesium ( Mg )	7439-95-4						0.495	mg	1500	384.77				
supplier	Leadframe	Silver (Ag)	7440-22-4						1.551	mg	4700	1205.61				
Glue Epoxy (EN-4900G)	Precious metals	2.049	mg					supplier	Glue or tape	Silver (Ag)	7440-22-4		1.547	mg	755000	1202.49
				supplier	Glue or tape	Cresol Novolac Epoxy Resins	Proprietary		0.051	mg	25000	39.82				
				supplier	Glue or tape	Bisphenol A Diacrylate	Proprietary		0.174	mg	85000	135.38				
				supplier	Glue or tape	Dicyclopentenyl group containing Acrylate	Proprietary		0.113	mg	55000	87.60				
				supplier	Glue or tape	Butadiene copolymer	Proprietary		0.020	mg	10000	15.93				
				supplier	Glue or tape	Polybutadiene epoxidized derivative	Proprietary		0.113	mg	55000	87.60				
				supplier	Glue or tape	Peroxy Ketals	Proprietary		0.010	mg	5000	7.96				
				supplier	Glue or tape	Substitutedalkoxyalkyl trimethoxysilane	Proprietary		0.010	mg	5000	7.96				
				supplier	Glue or tape	Methacrylate multialkoxy-substitutedalkyl ester	Proprietary		0.010	mg	5000	7.96				
				Bonding wire (Cu)	Precious metals	1.358	mg	supplier	Bonding wire	Copper (Cu)	7440-50-8		1.311	mg	965500	1018.94
supplier	Bonding wire	Palladium (Pd)	7440-05-3						0.042	mg	31000	32.72				
supplier	Bonding wire	Gold (Au)	7440-57-5						0.005	mg	3500	3.69				
Encapsulation (EME-G631SH)	M-011 Other inorganic materials	930.054	mg					supplier	Molding Compound	2,2'-((3,3',5,5'-Tetramethyl-1,1'-biphenyl)-4,4'-di	85954-11-6		37.202	mg	40000	28917.63
				supplier	Molding Compound	Epoxy resin	Proprietary		18.601	mg	20000	14458.82				
				supplier	Molding Compound	Phenol Resin	Proprietary		69.754	mg	75000	54220.56				
				supplier	Molding Compound	Silica(Amorphous) A	60676-86-0		659.873	mg	709500	512926.51				
				supplier	Molding Compound	Silica(Amorphous) B	7631-86-9		139.508	mg	150000	108441.12				
				supplier	Molding Compound	Carbon black	1333-86-4		5.115	mg	5500	3976.17				
External Plating (Sn)	M-011 Other inorganic materials	11.500	mg	supplier	Matte Sn	Tin (Sn)	7440-31-5		11.499	mg	999900	8938.18				
				supplier	Matte Sn	Impurities	Proprietary		0.001	mg	100	0.89				